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PRODUCT INFORMATION NOTIFICATION

PIN: PIN145328

Date: August 25, 2014

Subject: Changes to Two Port HX2VL™ Very Low Power USB 2.0 Hub Controllers.

To: PCN ADMIN
CYPRESS
pcn_adm@cypress.com

Change Type: Minor

Description of Change:

This notification is to inform customers about changes to the Two Port HX2VL™ Very Low Power USB 2.0 Hub Controllers.

HX2VL™ USB 2.0 family products are offered in two configurations, 1) Two Port Hub controller and 2) Four Port Hub controller. These two configurations use the same base die and their internal wire-bonds are configured to achieve Two Port and Four Port products.

It was discovered that the Two Port parts draw marginally more current compared to the Four Port parts. To reduce this high current to the level of Four Port parts, minor changes were done to the internal wire-bonding of the Two Port parts. No changes were done to the Four Port parts. This change does not affect the base die, netlist, form, fit, function or datasheet specifications. There will not be any changes to ordering part numbers.

Part Numbers Affected: 4

| Item | Affected Marketing Parts |
|------|--------------------------|
| 1 | CY7C65634-28LTXC |
| 2 | CY7C65634-28LTXCT |
| 3 | CY7C65634-48AXC |
| 4 | CY7C65634-48AXCT |

Approximate Implementation Date:

The changes in wire-bonding configuration were implemented in April 2014. All products manufactured after Date Code 1413 have the new bonding configuration.

Anticipated Impact:

A reduction in current (~40mA) will be observed on Two Port parts with the new wire-bonding configuration.

Products manufactured with the new wire-bonding configuration are completely compatible with existing product from a functional, datasheet parametric, and quality performance perspective.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:

All products manufactured after Date Code 1413 have the new bonding configuration.

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

This is an information only announcement. No response is required

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration